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# FACSIMILE COVER SHEET

Date: <b>June 16, 2003</b>	Client & Matter Number : <b>015114-052310US</b>	No. Pages (including this one): <b>2</b>
To: <b>Examiner Nitin Parekh Art Unit 2811 U.S. Patent and Trademark Office</b>	At Fax Number: <b>1 (703) 308-7722, 4</b>	Confirmation Phone Number:

From :

**Melvin D. Chan**

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JUN 16 2003

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Message:

TECHNOLOGY CENTER 2800

Re: **U.S. Patent Application 09/517,345 for  
METHOD AND STRUCTURE FOR INTEGRATED CIRCUIT PACKAGE**  
Our File: **+015114-052310US**

Dear Examiner Parekh:

Enclosed is our agenda for the interview tomorrow scheduled for 2:00 p.m. your time.

Melvin D. Chan

Original Will:	<input type="checkbox"/> BE SENT BY MAIL	<input type="checkbox"/> BE SENT BY FEDEX/OVERNIGHT COURIER	<input type="checkbox"/> BE SENT BY MESSENGER	<input checked="" type="checkbox"/> NOT BE SENT
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PA 3311868 v1

**Outline for Interview**  
Application No. 09/517,345

**1. Motivation to Combine**

- a. Zenner - Ultra-thin package  
Schueller - Standard thickness package
- b. Zenner - Flexibility after assembly  
Schueller - Package flatness and coplanarity
- c. Schueller - Decouple die from substrate  
Welkowsky - Directly bond die to substrate

**2. Discuss combination of (1) Schueller and (2) Zenner and (3) Welkowsky**

**3. Discuss potential allowable claim language**

- a. Examiner's suggestions
- b. Applicant's suggestions

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